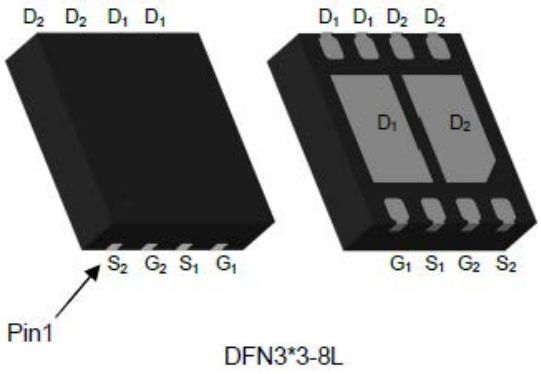
Dual N-Channel Enhancement Mode MOSFET

Feature

- 100V/10A
  $R_{DS(ON)}$= 74 mΩ(typ) @V_{GS} = 10V
  $R_{DS(ON)}$= 90 mΩ(typ) @V_{GS} = 4.5V
- 100% Avalanche Tested
- Reliable and Rugged
- Halogen Free and Green Devices Available (RoHS Compliant)

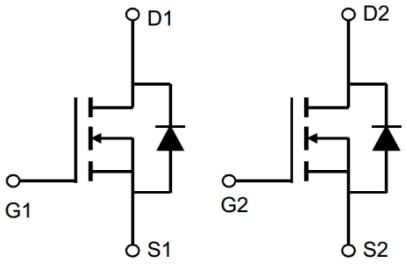
Pin Description



DFN3*3-8L

Applications

- Switching Application
- Power Management for DC/DC
- Battery Protection



Dual N-Channel MOSFET

Ordering and Marking Information

HMS10DN10Q YYWW	Package Code Q: DFN3*3-8L Date Code YYWW

Note:H&M Semi lead-free products contain molding compounds/die attach materials and 100% matte tin plateTermi-Nationfinish;which are fully compliant with RoHS.H&M Semi lead-free products meet or exceed the lead-Free require-ments of IPC/JEDEC J-STD-020 for MSL classification at lead-free peak reflow temperature.H&M Semi defines “Green” to mean lead-free (RoHS compliant) and halogen free (Br or Cl does not exceed 900ppm by weight in homogeneous material and total of Br and Cl does not exceed 1500ppm by weight).

Absolute Maximum Ratings

Symbol	Parameter		Rating	Unit
Common Ratings (Tc=25°C Unless Otherwise Noted)				
V_{DSS}	Drain-Source Voltage		100	V
V_{GSS}	Gate-Source Voltage		±20	V
T_J	Junction Temperature Range		-55 to 150	°C
T_{STG}	Storage Temperature Range		-55 to 150	°C
I_S	Source Current-Continuous(Body Diode)	Tc=25°C	10	A
Mounted on Large Heat Sink				
I_{DM}	Pulsed Drain Current *	Tc=25°C	30	A
I_D	Continuous Drain Current	Tc=25°C	10	A
		Tc=100°C	7	A
P_D	Maximum Power Dissipation	Tc=25°C	17.8	W
		Tc=100°C	7.1	W
$R_{\theta Jc}$	Thermal Resistance, Junction-to-Case		7	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient		75	°C/W
E_{AS}	SinglePulsed-Avalanche Energy **	L=0.1mH	10	mJ

Note: * R epetitive rating；pulse width limited by max.junction temperature.
** Limited by $T_J$max , starting T_J=25°C, L = 0.1mH, R_G= 25Ω, V_{GS} =10V.

Electrical Characteristics(Tc =25°C Unless Otherwise Noted)

Symbol	Parameter	Test Conditions	HMS24DN03Q			Unit
			Min	Typ.	Max	
Static Characteristics						
BV_{DSS}	Drain-Source Breakdown Voltage	V_{GS}=0V,I_{DS}=250μA	100	-		V
I_{DSS}	Drain-to-Source LeakageCurrent	V_{DS}=100V,V_{GS}=0V	-	-	1	μA
		T_J=125°C	-	-	50	μA
$V_{GS(th)}$	Gate Threshold Voltage	V_{DS}=V_{GS}, I_{DS}=250μA	1	1.8	2.5	V
I_{GSS}	Gate-Source Leakage Current	V_{GS}=±20V,V_{DS}=0V	-	-	±100	nA
$R_{DS(ON)}$*	Drain-Source On-State Resistance	V_{GS}=10V,I_{DS}=6A	-	74	85	mΩ
		V_{GS}=4.5V,I_{DS}=4A		90	115	
Diode Characteristics						
V_{SD}*	Diode Forward Voltage	I_{SD}=1A,V_{GS}=0V	-	0.7	1.0	V
t_{rr}	Reverse Recovery Time	I_{SD}=6A,dI_{SD}/dt=100A/μs	-	8	-	ns
Q_{rr}	Reverse Recovery Charge		-	19	-	nC

Electrical Characteristics (Cont.) (Tc =25°C Unless Otherwise Noted)

Symbol	Parameter	Test Conditions	HMS24DN03Q			Unit
			Min	Typ.	Max	
Dynamic Characteristics						
R_G	Gate Resistance	V_{GS}=0V,V_{DS}=0V,F=1 MHz	-	2.0	-	Ω
C_{iss}	Input Capacitance	V_{GS}=0V, V_{DS}=25V, Frequency=1.0MHz	-	354	-	pF
C_{oss}	Output Capacitance		-	59	-	
C_{rss}	Reverse Transfer Capacitance		-	36	-	
$t_{d(ON)}$	Turn-on Delay Time	V_{DD}=10V,R_G=4Ω, I_{DS}=6A,V_{GS}=10V	-	3.9	-	ns
T_r	Turn-on Rise Time		-	7.5	-	
$t_{d(OFF)}$	Turn-off Delay Time		-	15.6	-	
T_f	Turn-off Fall Time		-	4.6	-	
Gate Charge Characteristics						
Q_g	Total Gate Charge	V_{DS} =24V, V_{GS}=10V, I_D=6A	-	9	-	nC
Q_{gs}	Gate-Source Charge		-	1.2	-	
Q_{gd}	Gate-Drain Charge		-	2.3	-	

Note: *Pulse test，pulse width ≤ 300us，duty cycle ≤ 2%

Typical Operating Characteristics

Figure 1: Power Dissipation

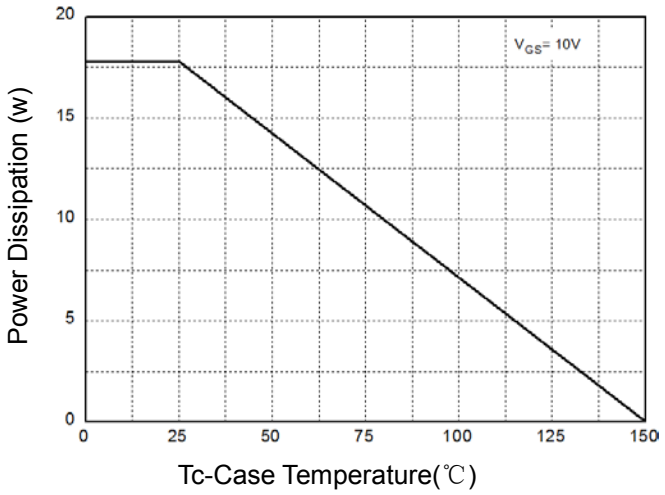


Figure 2: Drain Current

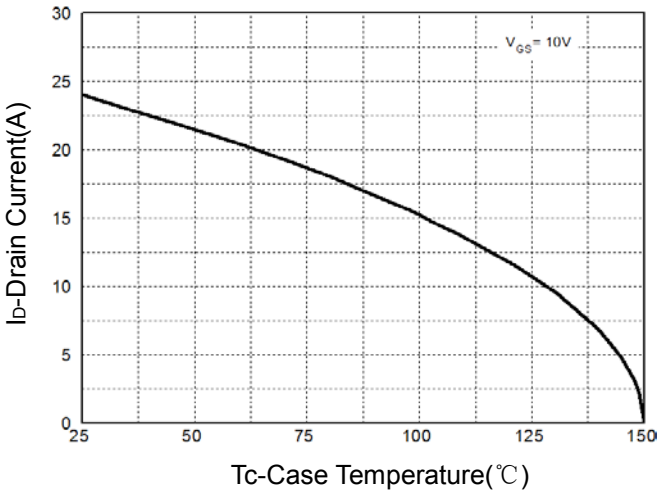


Figure 3: Safe Operation Area

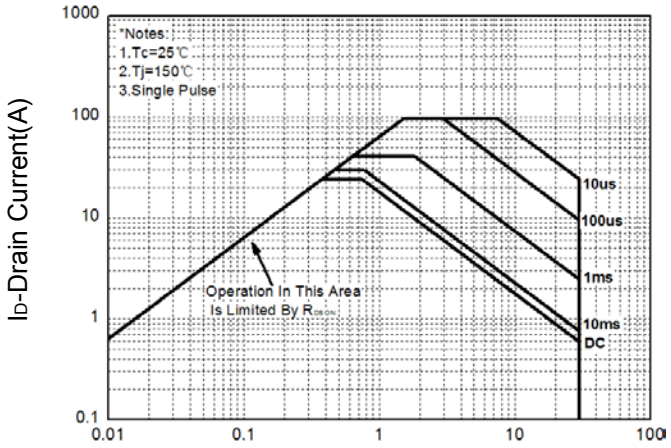
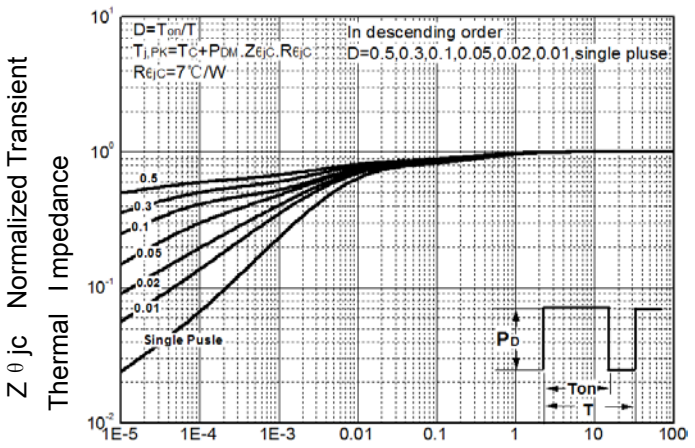


Figure 4: Thermal Transient Impedance



Maximum Effective Transient Thermal Impedance, Junction-to-Case

Figure 5: Output Characteristics

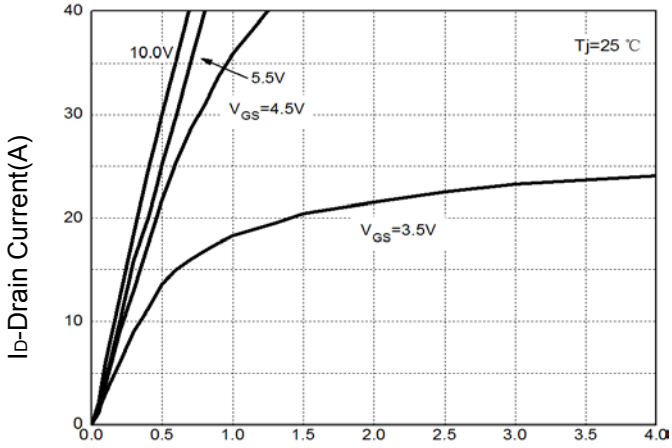
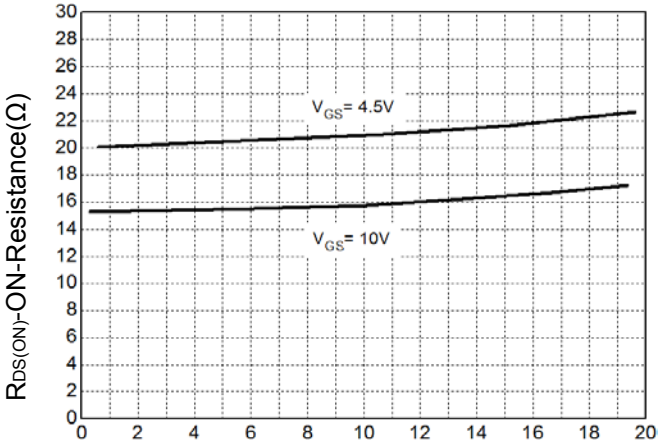
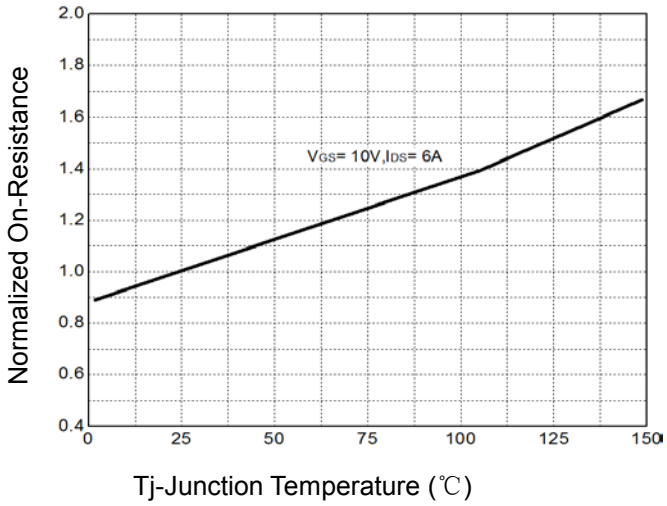


Figure 6: Drain-Source On Resistance



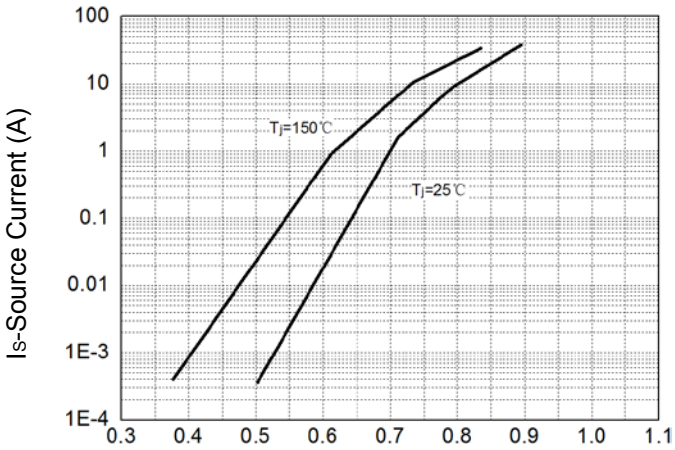
Typical Operating Characteristics

Figure 7: On-Resistance vs. Temperature



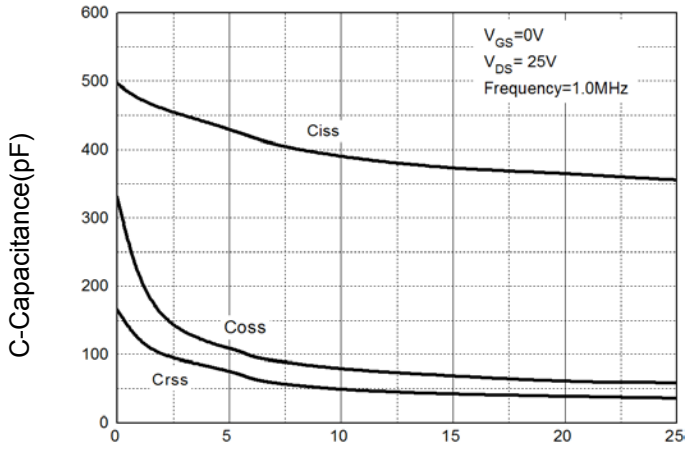
Tj-Junction Temperature (℃)

Figure 8: Source-Drain Diode Forward



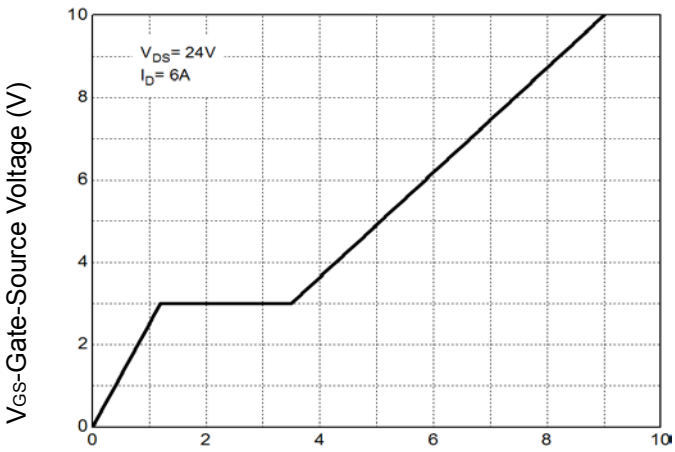
VSD-Source-Drain Voltage(V)

Figure 9: Capacitance Characteristics



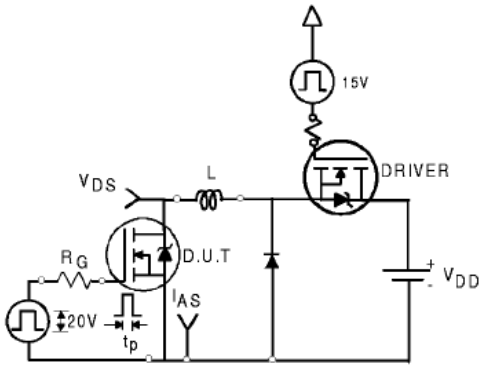
VDS-Drain-Source Voltage (V)

Figure 10: Gate Charge Characteristics

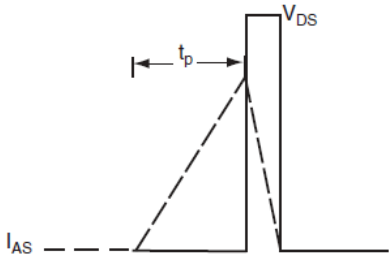


QG-Gate Charge (nC)

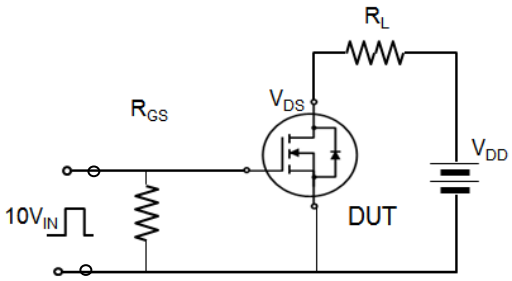
Avalanche Test Circuit

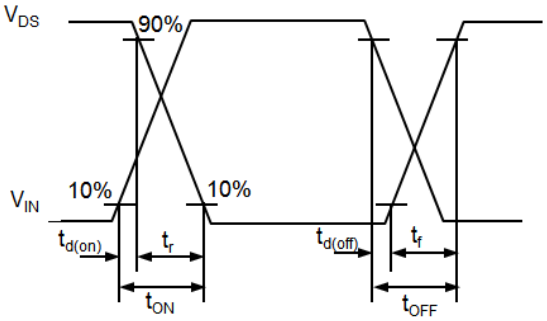


$$E_{AS} = \frac{1}{2} L I_{AS}^2$$

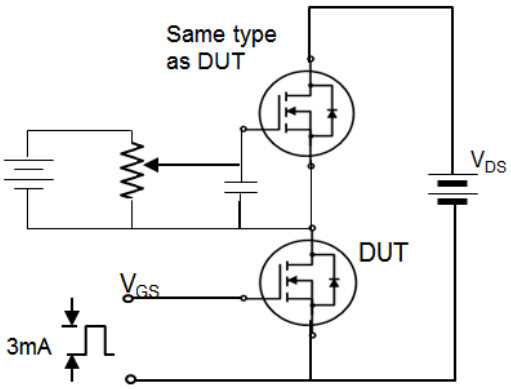


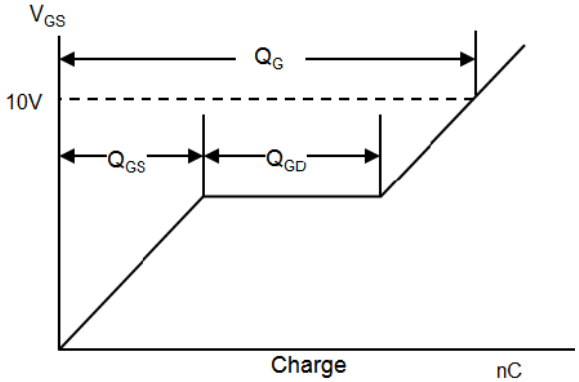
Switching Time Test Circuit





Gate Charge Test Circuit



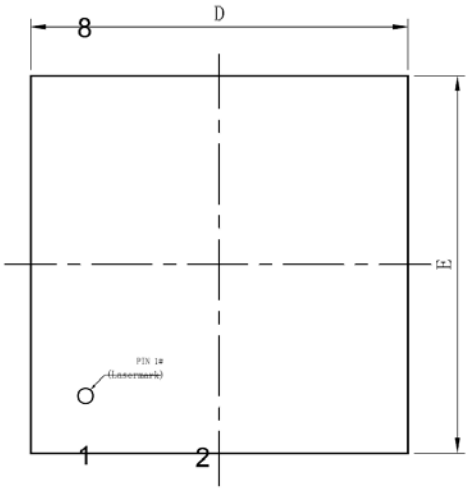


Device Per Unit

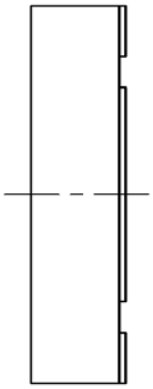
Package Type	Unit	Quantity
DFN3*3-8L	Reel	3000

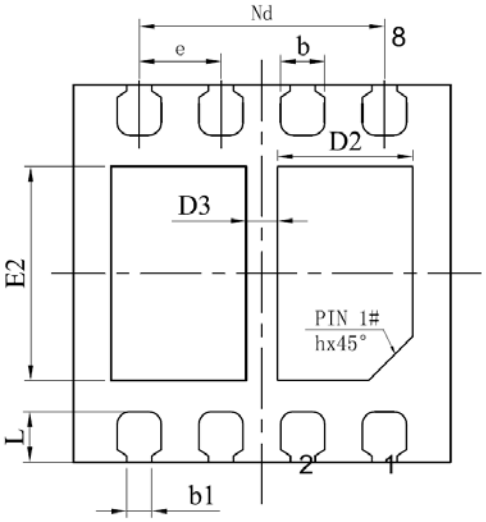
Package Information

DFN3*3-8L

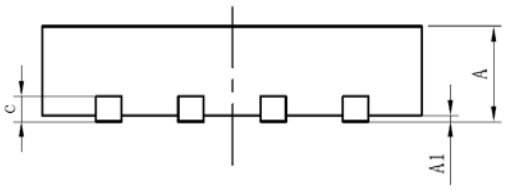


TOP VIEW





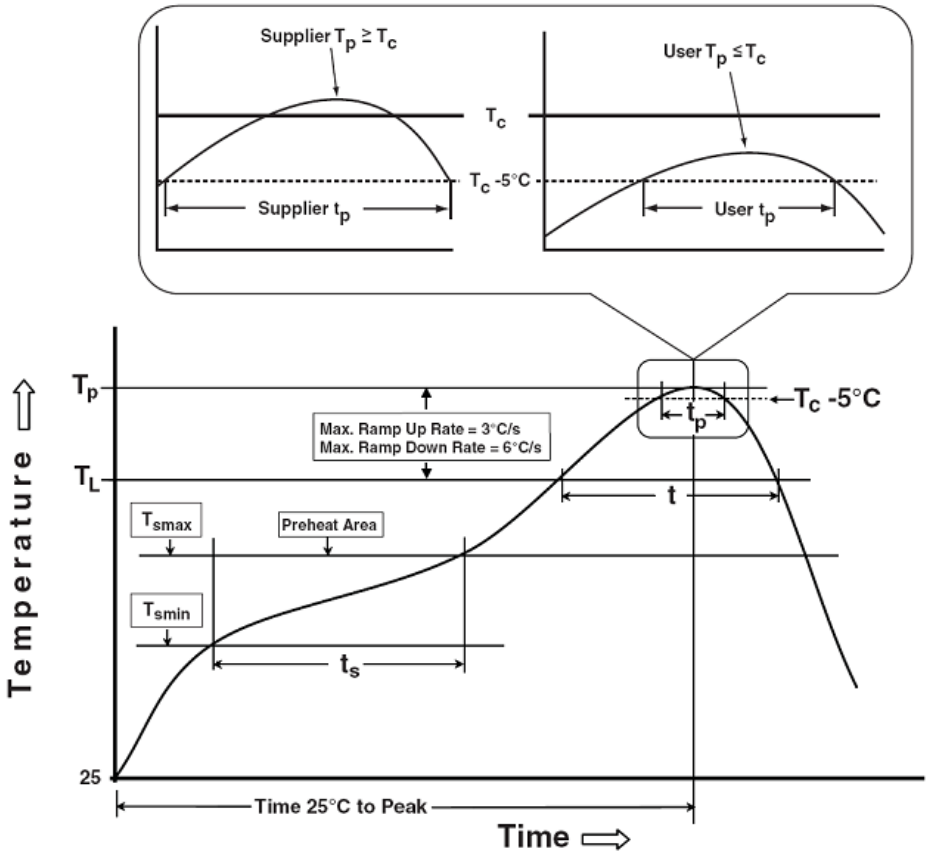
BOTTOM VIEW



SIDE VIEW

SYMBOL	MILLIMETER		
	MIN	NOM	MAX
A	0.70	0.75	0.80
A1	0.00	0.02	0.05
b	0.25	0.30	0.35
b1		0.20REF	
c	0.18	0.20	0.23
D	2.90	3.00	3.10
D2	0.975	1.075	1.175
D3		0.25REF	
Nd	1.90	1.95	2.00
E	2.90	3.00	3.10
E2	1.60	1.70	1.80
e		0.65BSC	
L	0.35	0.40	0.45
h	0.30	0.35	0.40

Classification Profile



Classification Reflow Profiles

Profile Feature	Sn-Pb Eutectic Assembly	Pb-Free Assembly
Preheat & Soak Temperature min (T_{smin}) Temperature max (T_{smax}) Time (Tsmin to Tsmax) (t_s)	 100 °C 150 °C 60-120 seconds	 150 °C 200 °C 60-120 seconds
Average ramp-up rate ($T_{smax}$to T_P)	3 °C/second max.	3°C/second max.
Liquidous temperature (T_L) Time at liquidous (t_L)	183 °C 60-150 seconds	217 °C 60-150 seconds
Peak package body Temperature (T_p)*	See Classification Temp in table 1	SeeClassification Tempin table 2
Time (t_P)** within 5°C of the specified classification temperature (T_c)	20** seconds	30** seconds
Average ramp-down rate ($T_p$to T_{smax})	6 °C/second max.	6 °C/second max.
Time 25°C to peak temperature	6 minutes max.	8 minutes max.
*Tolerance for peak profile Temperature (T_p) is defined as a supplier minimum and a user maximum. ** Tolerance for time at peak profile temperature (t_p) is defined as a supplier minimum and a user maximum.		

Table 1.SnPb Eutectic Process – Classification Temperatures (Tc)

Package Thickness	Volume mm³ <350	Volume mm³ ⩾350
＜2.5 mm	235 °C	220 °C
≥2.5 mm	220 °C	220 °C

Table 2.Pb-free Process – Classification Temperatures (Tc)

Package Thickness	Volume mm³ <350	Volume mm³ 350-2000	Volume mm³ ⩾2000
<1.6 mm	260 °C	260 °C	260 °C
1.6 mm – 2.5 mm	260 °C	250 °C	245 °C
⩾2.5 mm	250 °C	245 °C	245 °C

Reliability Test Program

Test item	Method	Description
SOLDERABILITY	JESD-22, B102	5 Sec, 245°C
HTRB	JESD-22, A108	168 Hrs \ 500Hrs\ 1000 Hrs, Bias @ 125°C
PCT	JESD-22, A102	96 Hrs, 100%RH, 2atm, 121°C
TCT	JESD-22, A104	500 Cycles, -55°C~150°C